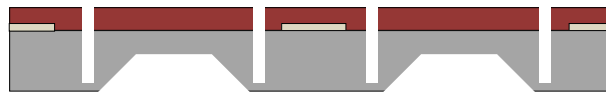




(a) Top side lithography on silicon (100) wafer



(b) Membrane realization by KOH etching



(c) Back side lithography, DRIE etching of fluidic holes



(d) DRIE etching of fluidic cells, thermal oxidation



(e) Electrodes deposition, back side lithography



(f) Metal etching and photoresist dissolution

Photoresist
  Al
  SiO<sub>2</sub>
 Cr/Au